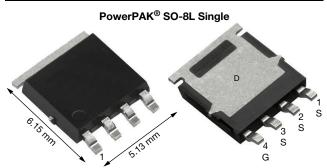
Vishay Siliconix

## N-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω) Max.	I <sub>D</sub> (A) a, g	Q <sub>g</sub> (Typ.)		
40	0.00135 at V <sub>GS</sub> = 10 V	80	58 nC		
	0.00175 at V <sub>GS</sub> = 4.5 V	80	36110		



**Bottom View** 

### **Ordering Information:**

Top View

SiJ438DP-T1-GE3 (lead (Pb)-free and halogen-free)

#### **FEATURES**

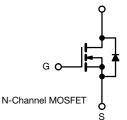
- TrenchFET® Gen IV power MOSFET
- Tuned for the lowest R<sub>DS</sub>-Q<sub>oss</sub> FOM
- 100 % Rq and UIS tested
- Q<sub>gd</sub> / Q<sub>gs</sub> ratio < 1 optimizes switching characteristics





#### **APPLICATIONS**

- Synchronous rectification
- ORing
- High power density DC/DC
- VRMs and embedded DC/DC
- DC/AC inverters
- · Load switch



<b>ABSOLUTE MAXIMUM RATINGS (</b>	$T_A = 25  ^{\circ}C$ , unless	otherwise note	d)		
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V <sub>DS</sub>	40	V	
Gate-Source Voltage		$V_{GS}$	+20, -16	V	
	T <sub>C</sub> = 25 °C		80 g		
Continuous Drain Comment (T. 150 °C)	T <sub>C</sub> = 70 °C	l , 🗀	<b>80</b> g		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	45.3 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		36.2 b, c	^	
Pulsed Drain Current (t = 100 μs)		I <sub>DM</sub>	200	— A	
Continuous Common Dunio Dio do Commont	T <sub>C</sub> = 25 °C		63		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	4.5 <sup>b, c</sup>		
Single Pulse Avalanche Current	che Current		50		
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	125	mJ	
	T <sub>C</sub> = 25 °C		69.4		
Manian and Danier Disable at land	T <sub>C</sub> = 70 °C		44.4	14/	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	5 b, c	— w	
	T <sub>A</sub> = 70 °C		3.2 b, c		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Soldering Recommendations (Peak Temperature) d, e			260		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient b, f	t ≤ 10 s	R <sub>thJA</sub>	20	25	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R <sub>thJC</sub>	1.3	1.8	C/W	

#### Notes

- a.  $T_C = 25$  °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under steady state conditions is 65 °C/W.
- g. Package limited.



# Vishay Siliconix

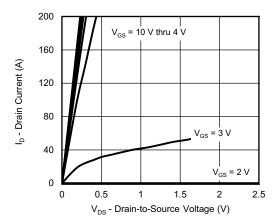
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	vn Voltage $V_{DS}$ $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		40	-	-	V
V <sub>DS</sub> Temperature Coefficient	AVne/Tu		-	22	-	14/00
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA	-	-5.6	-	mV/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.1	-	2.4	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = +20 \text{ V}, -16 \text{ V}$	-	-	± 100	nA
Zama Oata Waltana Busin Ourmant		V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V	-	-	1	μΑ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C	-	-	10	
On-State Drain Current a	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30	-	-	Α
Dunin Course On Chata Basistana 3	0	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A	-	0.00110	0.00135	Ω
Drain-Source On-State Resistance a	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$	-	0.00145	0.00175	
Forward Transconductance a	9 <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	149	-	S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>		-	9400	-	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	1340	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	215	-	
Total Cata Chausa		$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	-	121	182	
Total Gate Charge	$Q_g$		-	58	87	
Gate-Source Charge	$Q_{gs}$ $V_{DS} = 20 \text{ V}, V_{GS} = 4.5$	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$	-	22.6	-	nC
Gate-Drain Charge	$Q_{gd}$	1		13.5	-	
Output Charge	Q <sub>oss</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	-	62.5	94	
Gate Resistance	Rg	f = 1 MHz	0.4	1.1	2.0	Ω
Turn-On Delay Time	t <sub>d(on)</sub>		-	16	32	
Rise Time	t <sub>r</sub>	$V_{DD} = 20 \text{ V}, R_L = 2 \Omega$	-	19	38	-
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong 10~A,~V_{GEN}=10~V,~R_g=1~\Omega$	-	54	108	
Fall Time	t <sub>f</sub>		-	9	18	
Turn-On Delay Time	t <sub>d(on)</sub>		-	55	110	ns
Rise Time	t <sub>r</sub>	$V_{DD} = 20 \text{ V}, R_L = 2 \Omega$	-	98	196	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong 10$ A, $V_{GEN}=4.5$ V, $R_g=1~\Omega$	-	47	94	İ
Fall Time	t <sub>f</sub>		-	17	34	
<b>Drain-Source Body Diode Characteristic</b>	s					
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	-	-	63	
Pulse Diode Forward Current (t = 100 μs)	I <sub>SM</sub>		-	-	200	A
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 5 A	-	0.7	1.1	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>		-	60	120	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	1 10 A 31/31 100 A/ 5 T 05 00	-	95	190	nC
Reverse Recovery Fall Time	ta	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$	-	33	-	
Reverse Recovery Rise Time			-	27	-	ns

#### Notes

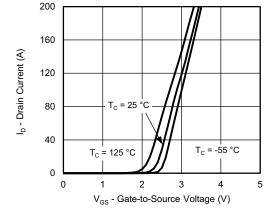
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

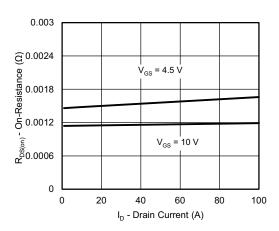




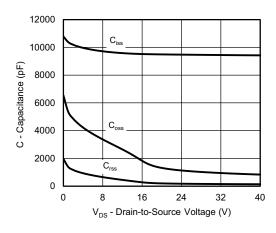
#### **Output Characteristics**



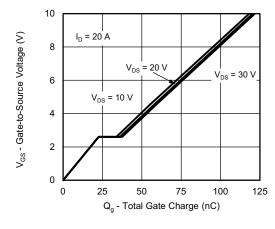
**Transfer Characteristics** 



On-Resistance vs. Drain Current

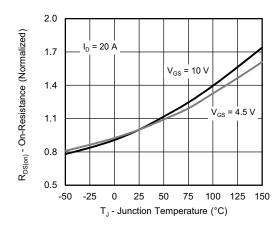


Capacitance

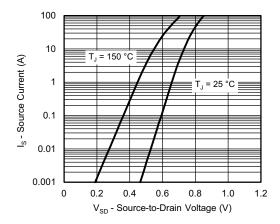


**Gate Charge** 

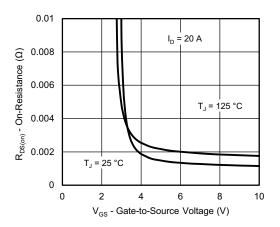
On-Resistance vs. Junction Temperature



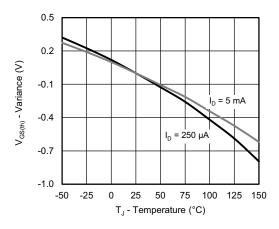




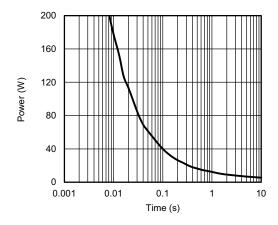
Source-Drain Diode Forward Voltage



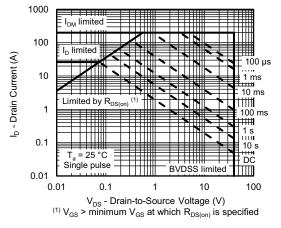
On-Resistance vs. Gate-to-Source Voltage



**Threshold Voltage** 

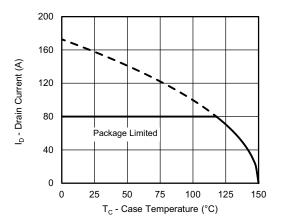


Single Pulse Power, Junction-to-Ambient

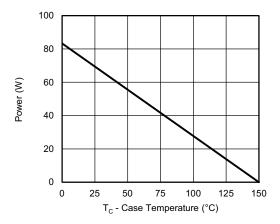


Safe Operating Area, Junction-to-Ambient

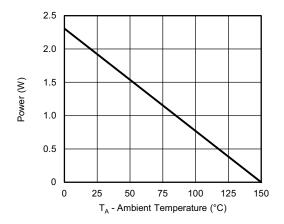




### Current Derating a





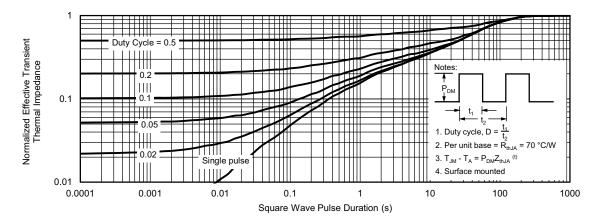


Power, Junction-to-Ambient

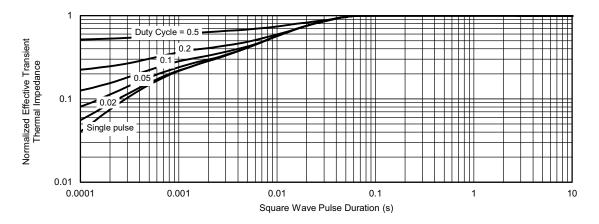
#### Note

a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> (max.) = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





#### Normalized Thermal Transient Impedance, Junction-to-Ambient

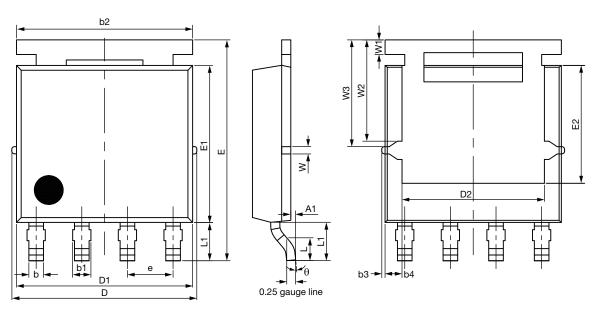


Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?69684">www.vishay.com/ppg?69684</a>.

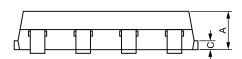


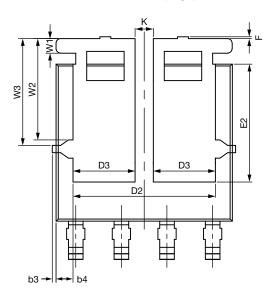
# PowerPAK® SO-8L Case Outline 1



Topside view

Backside view (single)





Backside view (dual)

Revision: 05-Aug-2019 1 Document Number: 69003



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DIM.	MILLIMETERS			INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC	•	0.050 BSC			
Е	6.05	6.15	6.25	0.238	0.242 0.246		
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	3.18	3.28	3.38	0.125	0.129	0.133	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K	0.51			0.020			
W	0.23			0.009			
W1	0.41			0.016			
W2	2.82			0.111			
W3	2.96			0.117			
θ	0°	-	10°	0°	-	10°	

ECN: S19-0643-Rev. E, 05-Aug-2019

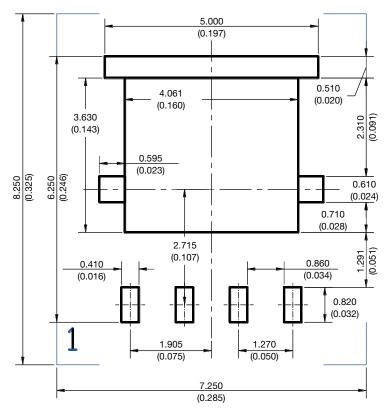
DWG: 5976

#### Note

• Millimeters will gover



### RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)

## **Legal Disclaimer Notice**



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